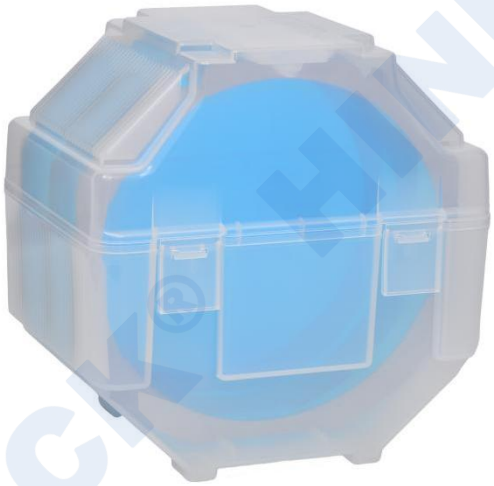
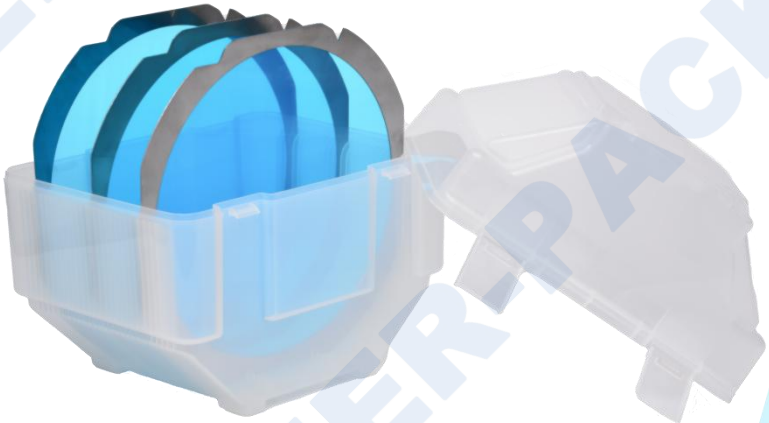
Hiner-pack® FVWS Canister 200 mm

Reliable wafer shipping solution ensuring protection from contamination and mechanical damage



This vertical flex frame wafer shipper is engineered for the safe transport of wafers mounted on dicing, flex, or film frames. Its precision slot design keeps frames upright and immobilized, while interior contours cradle the frame's edge to prevent wafer surface contact, avoiding scratches and micro-cracks. A spring mechanism in the upper cover prevents movement, ensuring wafers remain stable during transit. Constructed from high-purity polymer, the shipper minimizes ionic contamination, outgassing, and particle generation. Each unit undergoes dust-free cleaning and Class 100 purification packaging, delivering contamination-free wafer storage and reliable protection for high-value semiconductor wafers during shipment.



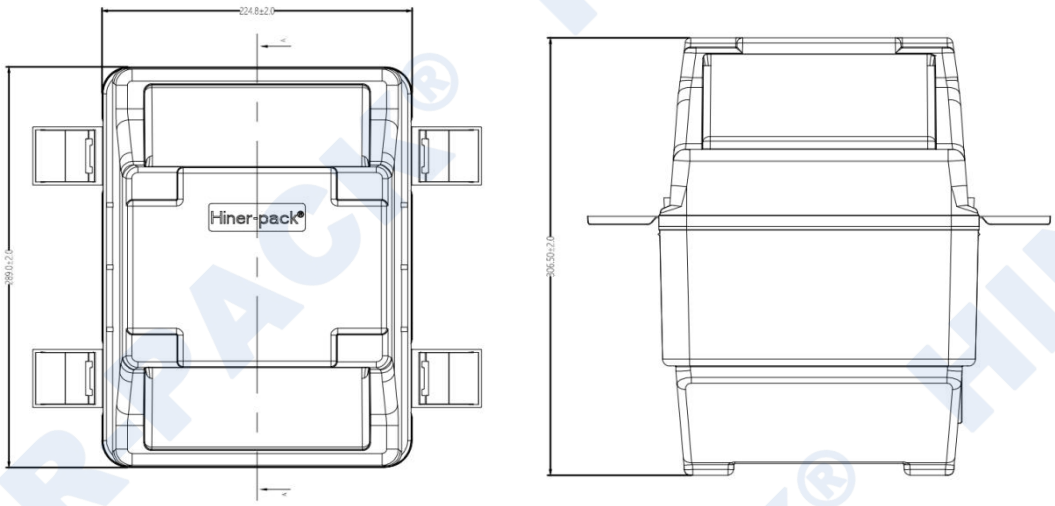
SPECIFICATIONS

- 289 mm L × 224.8 mm W × 306.5 mm H (11.38" × 8.85" ×12.04")
- Maximum load capacity is 25 pieces
- Sold in full case quantity (4)

FEATURES & BENEFITS

- Made from low particle/ionic/outgassing material
- Vertical secures wafers already mounted on flex, dicing, or film frame
- Spring design in the upper cover can effectively avoid the frames movement, prevent wafer breakage
- Reusable for cost-efficient shipping

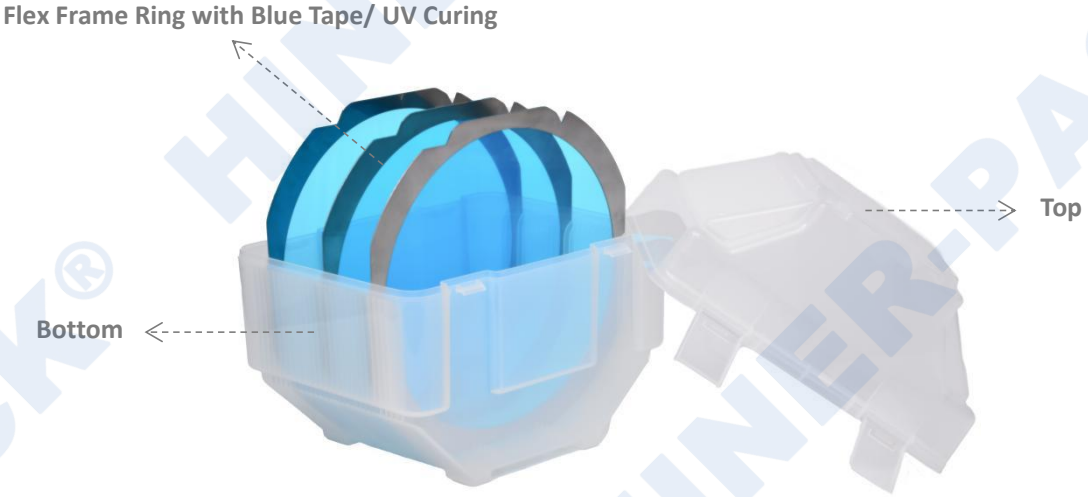
DIMENSION



BASIC INFORMATION

Part Number	Collocation Reference	Wafer Size
FVWS-8/25-BL	Bottom+Frame+Top	200 mm

REFERENCE ILLUSTRATION



The above illustration is for reference only. Please refer to the actual product for accuracy.

TECHNICAL DATA

PROPERTY	TEST METHOD	RATED VALUES
Density	ISO 1183	0.9 g/cm³
Melt Index	ISO 1133	15 g/10min
Melting Point	DSC	146°C
Distortion Temperature	ISO 75	95°C
Vicat softening temperature	ISO 306	125°C
Tensile Strength at Yield	ISO 527	280 kg/m²
Tensile Elongation at Break	ISO 527	300 %
Rockwell hardness R scale	ISO 2039	98
Tensile Strain at Break	ISO 527-2 (50mm/min)	10 %
Flexural Modulus	ISO 178	10500 kg/m²
Flow Shrinkage	FPC Method	1.3~1.7 %
LZOD Impact Strength	ISO 180 23°C	6 kg.cm/cm
	ISO 180 -20°C	--- notch

The information on technical data included in this document is based on our experience to date, and we believe it to be reliable. Data is obtained from specimens molded under controlled conditions from representative samples of the compound described. Properties may be affected by the molding techniques and by the size and shape of the item molded. We cannot guarantee favorable results and no assurances can be implied that all molded articles have the sample properties as those listed.

Hiner-pack®

Corporate Headquarters

Bldg A11, Zone D, West Industrial Zone,
Minzhu Comm., Shajing St., Bao'an,
Shenzhen, Guangdong, China

Customer Service

Tel +86 755 2322 9236
Fax +86 755 2996 0455
Work Time 08:00 - 18:00 (Beijing Time/UTC+8)